

Features

Single Biasing Voltage (Self Biased)

• Frequency: 2-18GHz

Small Signal Gain: 24dB Typical
 Gain Flatness: ±2.0dB Typical
 Noise Figure:1.3dB Typical

• P1dB: 15dBm Typical

• Power Supply: +5V@54mA

• Input/Output: 50Ω

• Chip Size: 1.796 x 1.038 x 0.1mm

Typical Application

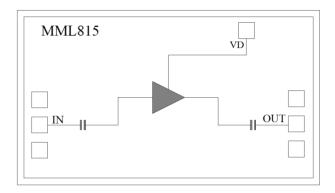
- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

Electrical Specifications

TA = +25°C, VD = +5V, IDD = 54mA Typical

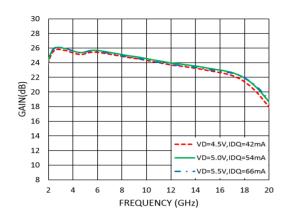
Parameters	Min.	Тур.	Max.	Min.	Тур.	Max.	Units
Frequency	2		12	12		18	GHz
Small Signal Gain	23	25		21	23		dB
Gain Flatness		±1.5			±1.0		dB
Noise Figure		1.3			1.7		dB
P1dB - Output 1dB Compression	10	15		12	14		dBm
Psat - Saturated Output Power		15.5			16		dBm
OIP3 - Output Third Order Intercept		25			25		dBm
Input Return Loss		-17			-17		dB
Output Return Loss		-15			-15		dB

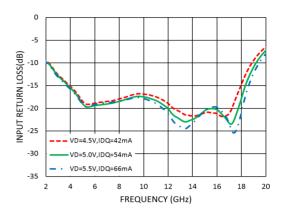
Functional Block Diagram

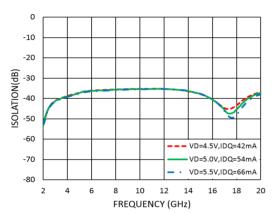


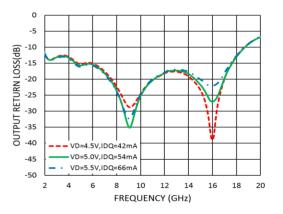


Measurement Plots: S-parameters

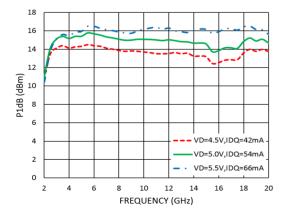




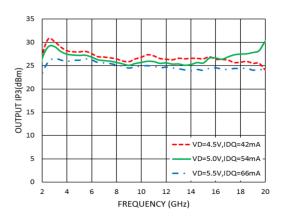




Measurement Plots: P1dB



Measurement Plots: OIP3

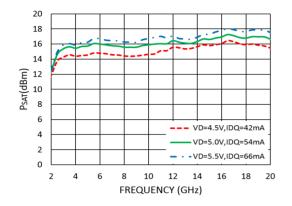


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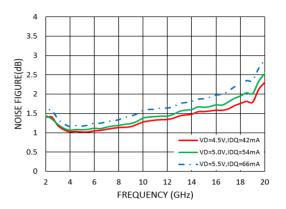
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Measurement Plots: PSAT



Measurement Plots: Noise Figure



Absolute Maximum Ratings

Drain Bias Voltage (VD)	+6V
RF Input Power (RFIN)@(+5V)	+10dBm
Channel Temperature	220°C
Continuous Pdiss (T = 85 °C) (derate 5.2mW/°C above 85 °C)	0.47W
Thermal Resistance (channel to die bottom)	50°C/W
Operating Temperature	-40°C to +85°C
Storage Temperature	-65°C to +150°C

Typical Supply Current vs. VD

VD (V)	IDD (mA)
+4.5	42
+5.0	54
+5.5	66

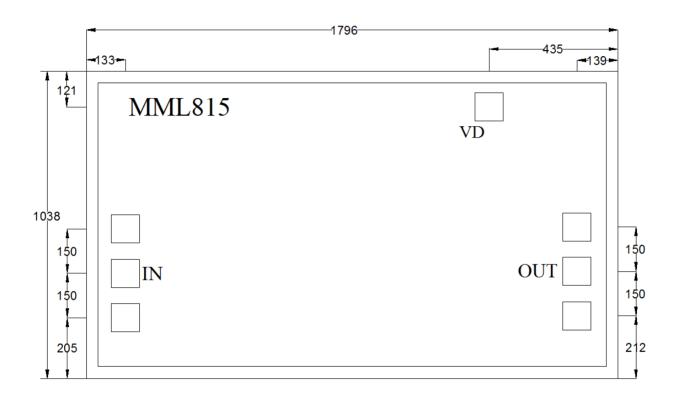


ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS



Outline Drawing:

All Dimensions in µm



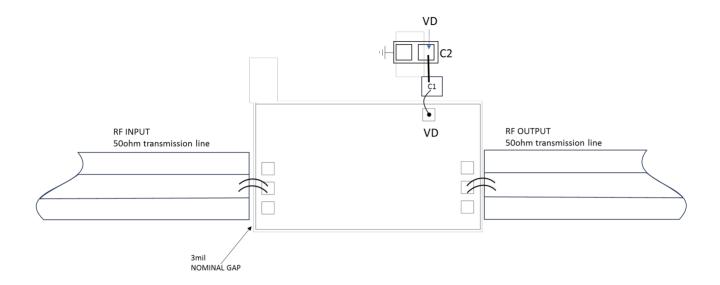
Notes:

Die thickness: 100μm
 DC bond pad is 95*95μm²

3. RF IN/OUT bond pad is 95*95μm²
4. Bond pad metalization: Gold
5. Backside metalization: Gold



Assembly Drawing



Item	Description
C1	100pF Example: Presidio Part: MVB3030X103M2H5C1
C2	1μF Example: KYOCERA AVX Part:116XK102M100TT

No	Function	Description
1	RF IN	RF signal input terminal; no blocking capacitor required.
2	RF OUT	RF signal output terminal; no blocking capacitor required.
3	VD	Drain Biases for the Amplifier. External bypass capacitors of $1\mu f$ and $100pf$ are required for these pads.
4	Die Bottom	Die bottom must be connected to RF and dc ground.

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VD
OUT

Biasing and Operation

Turn ON procedure:

- Connect GND to RF and dc ground.
- 2. Apply positive drain voltage VD and set to +5V.
- 3. Apply RF signal.

Turn OFF procedure:

- 1. Turn off the RF signal.
- 2. Turn off the positive drain voltage VD.

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